Product data sheet

1. General description

Hyperfast power diode in a 2-lead TO247 (SOD142) plastic package.

2. Features and benefits

- Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- · Low leakage current
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT
- High operating temperature capability (T_{j (max)} = 175°C)

3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values		Unit		
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage		600		V		
$I_{F(AV)}$	average forward current	$δ = 0.5$; square-wave pulse; $T_{mb} \le 116$ °C; Fig. 1; Fig. 2; Fig. 3	60		А		
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 μs; T_{mb} ≤ 116 °C; square-wave pulse	120		А		
I _{FSM} non-repetitive peak forward current		t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	600			А	
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;	660		Α		
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
V _F	forward voltage	I _F = 60 A; T _j = 25 °C; <u>Fig. 6</u>		-	2	2.4	V
		I _F = 60 A; T _j = 150 °C; <u>Fig. 6</u>		-	1.55	2	V
Dynamic	characteristics						
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A/}\mu\text{s};$ $T_i = 25 \text{ °C}; Fig. 7$		-	-	50	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		K — A 001aaa020
2	Α	anode		001aaa020
mb	mb	mounting base; connected to cathod	1 2	

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYC60W-600P	TO247-2L	BYC60W-600PQ	Tube	30	SOD142	27-Nov-2012

7. Marking

Table 4. Marking codes

Type number	Marking codes
BYC60W-600P	BYC60W-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
I _{F(AV)}	average forward current	$δ$ = 0.5 ; square-wave pulse; $T_{mb} \le 116$ °C; Fig. 1; Fig. 2; Fig. 3	60	А
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 116 °C; square-wave pulse	120	А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	600	А
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;	660	А
l ² t	limiting Joule-integral	SIN; t _p = 10 ms	1800	A ² s
T _{stg}	storage temperature		-55 to 175	°C
T _j	junction temperature		175	°C

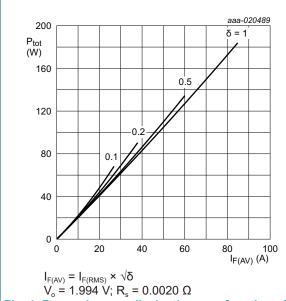
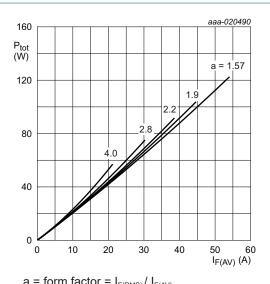


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)}/I_{F(AV)}$ Vo = 1.994 V; Rs = 0.0020 Ω Fig. 2. Forward power dissipation a

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

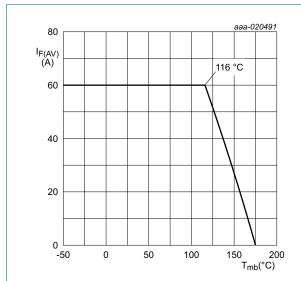


Fig. 3. Forward current as a function of mounting base temperature; maximum values

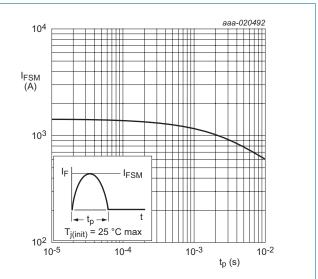
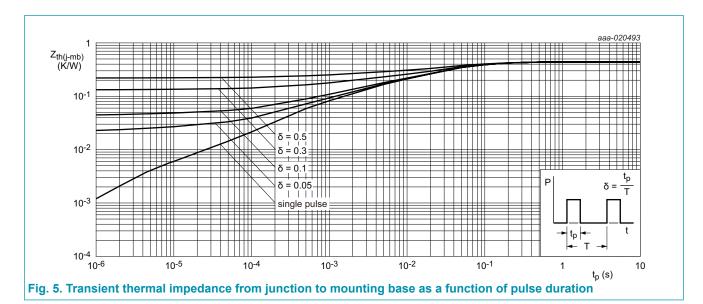


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

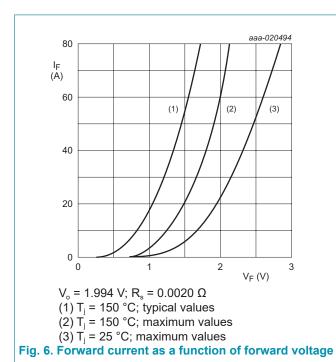
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 5	-	-	0.44	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static ch	aracteristics			'		
V _F fo	forward current	I _F = 60 A; T _j = 25 °C; <u>Fig. 6</u>	-	2	2.4	V
		I _F = 60 A; T _j = 150 °C; <u>Fig. 6</u>	-	1.55	2	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C	-	2	10	μA
		V _R = 600 V; T _j = 150 °C	-	-	500	μA
Dynamic	characteristics			'		
Q _r re	reverse charge	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	74	-	nC
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	559	-	nC
t _{rr} 1	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	50	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	40	-	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	101	-	ns
I _{RM}	peak reverse recovery current	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_J = 25 \text{ °C}; Fig. 7$	-	3.7	-	А
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	11	-	А



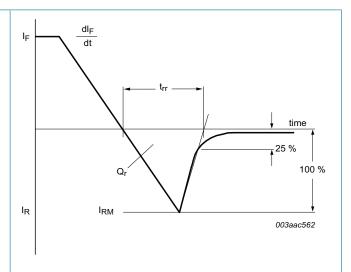
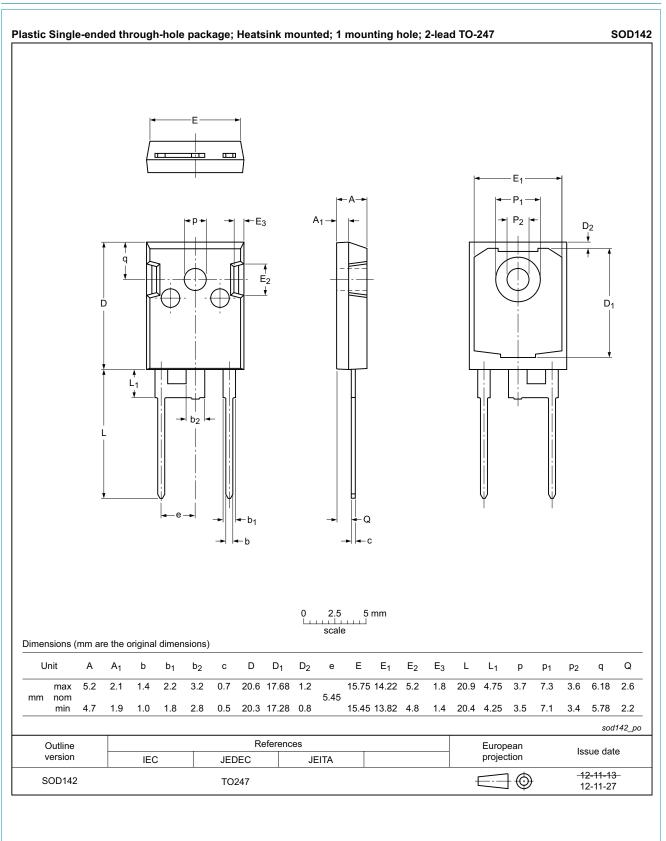


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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	Features and benefits

For more information, please visit: http://www.ween-semi.com
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